

STAND-ALONE CAN CONTROLLER

(Functional equivalent MCP2515 Microchip)

IN2515 is a stand-alone Controller Area Network (CAN) controller that implements the CAN specification, version 2.0B

The IC is designed to perform data receiving-transmitting in automotive and industrial applications.

IN2515

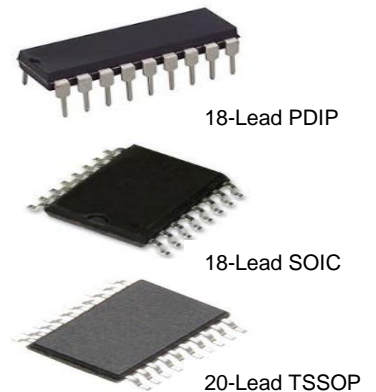


Fig. 1 Package Types

FEATURES

- Supply voltage range V_{CC} :
 - for IN2515AN, IN2515ADW 2.7 ... 5.5 V,
 - for IN2515BN, IN2515BDW; 4.5 ... 5.5 V
- Three transmit buffers with prioritization and abort features of the transmittance
- Two receive buffers with prioritized message storage
 - Six 29-bit filters
 - Two 29-bit masks
- High-speed SPI Interface (10MHz):
 - SPI modes 0.0 and 1.1
- Implements CAN V2.0B at 1 Mb/s:
 - 0 – 8 byte length in the data field
 - Standard and extended data and remote frames
 - Data byte filtering on the first two data bytes

ORDERING INFORMATION

Device	Operating Temperature Range	Package	Packing
IN2515AN	$T_A = -40^\circ$ to 85° C	DIP-18	Tube
IN2515ADT		SOP-18	Tape & Reel
IN2515ATSDT		TSSP-20	Tube & Reel
IN2515BN	$T_A = -40^\circ$ to 125° C	DIP-18	Tube
IN2515BDT		SOP-18	Tape & Reel

PIN LAYOUT

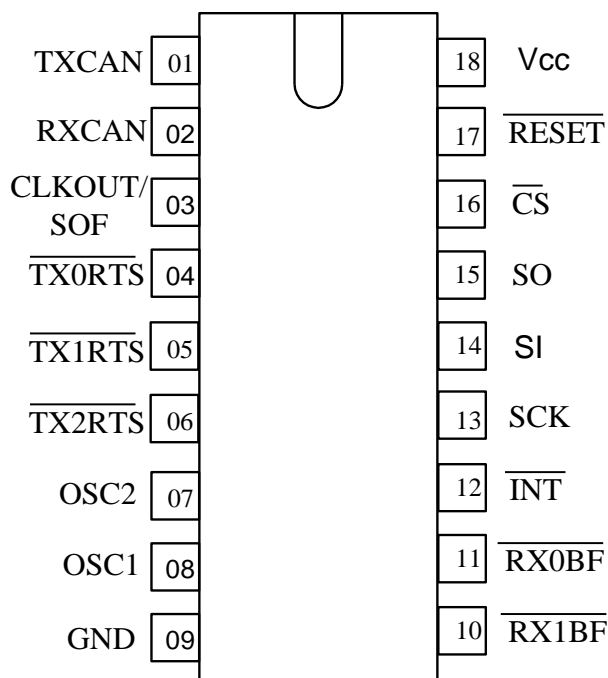


Fig. 2 – IN2515BN, IN2515AN Pin Layout

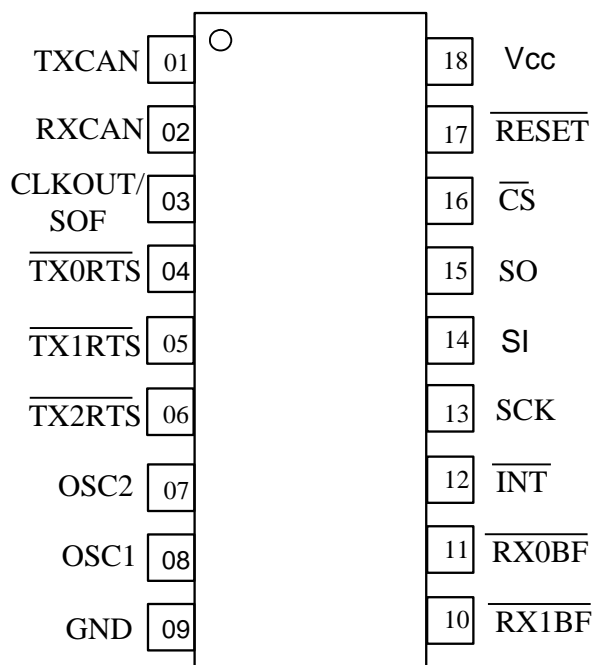


Fig 3 – IN2515BDW, IN2515ADW Pin Layout

Table 1. 18-Lead PDIP / SOIC Package Pin Description

Pin Number	Symbol	Function
01	TXCAN	Transmit output pin to CAN bus
02	RXCAN	Receive input pin from CAN bus
03	CLKOUT / SOF	Clock output pin with programmable prescaler
04	$\overline{\text{TX0RTS}}$	Transmit buffer TXB0 request-to-send. 100 k Ω internal pull-up to VDD
05	$\overline{\text{TX1RTS}}$	Transmit buffer TXB1 request-to-send. 100 k Ω internal pull-up to VDD
06	$\overline{\text{TX2RTS}}$	Transmit buffer TXB2 request-to-send. 100 k Ω internal pull-up to VDD
07	OSC2	Oscillator output (Quartz resonator connection)
08	OSC1	Oscillator input (Quartz resonator or external clock connection)
09	GND	Common pin (Ground)
10	$\overline{\text{RX1BF}}$	Receive buffer RXB1 interrupt pin or general purpose digital output
11	$\overline{\text{RX0BF}}$	Receive buffer RXB0 interrupt pin or general purpose digital output
12	$\overline{\text{INT}}$	Interrupt output pin
13	SCK	SPI Clock input pin for SPI interface
14	SI	Data input pin for SPI interface
15	SO	Data output pin for SPI interface
16	$\overline{\text{CS}}$	Chip select input pin for SPI interface
17	$\overline{\text{RESET}}$	Active low device reset input
18	V _{CC}	Positive supply for logic and I/O pins
Notes 1 CAN – Controller Area Network 2 SPI – Serial Peripheral Interface		

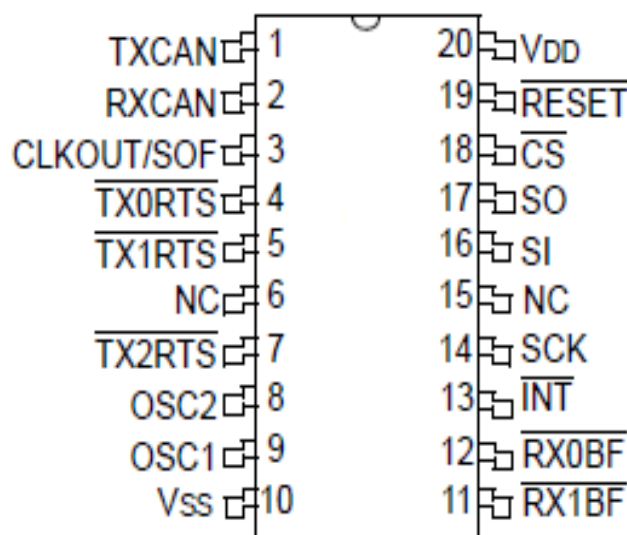


Fig 4 – IN2515ATSD Pin Layout

Table 2. 20-Lead TSSOP Package Pin Description

Pin Number	Symbol	Function
01	TXCAN	Transmit output pin to CAN bus
02	RXCAN	Receive input pin from CAN bus
03	CLKOUT / SOF	Clock output pin with programmable prescaler
04	$\overline{\text{TX0RTS}}$	Transmit buffer TXB0 request-to-send. 100 k Ω internal pull-up to VDD
05	$\overline{\text{TX1RTS}}$	Transmit buffer TXB1 request-to-send. 100 k Ω internal pull-up to VDD
06	NC	
07	$\overline{\text{TX2RTS}}$	Transmit buffer TXB2 request-to-send. 100 k Ω internal pull-up to VDD
08	OSC2	Oscillator output (Quartz resonator connection)
09	OSC1	Oscillator input (Quartz resonator or external clock connection)
10	GND	Common pin (Ground)
11	$\overline{\text{RX1BF}}$	Receive buffer RXB1 interrupt pin or general purpose digital output
12	$\overline{\text{RX0BF}}$	Receive buffer RXB0 interrupt pin or general purpose digital output
13	$\overline{\text{INT}}$	Interrupt output pin
14	SCK	SPI Clock input pin for SPI interface
15	NC	
16	SI	Data input pin for SPI interface
17	SO	Data output pin for SPI interface
18	$\overline{\text{CS}}$	Chip select input pin for SPI interface
19	$\overline{\text{RESET}}$	Active low device reset input
20	V _{cc}	Positive supply for logic and I/O pins
Notes		
1 CAN – Controller Area Network		
2 SPI – Serial Peripheral Interface		

BLOCK DIAGRAM

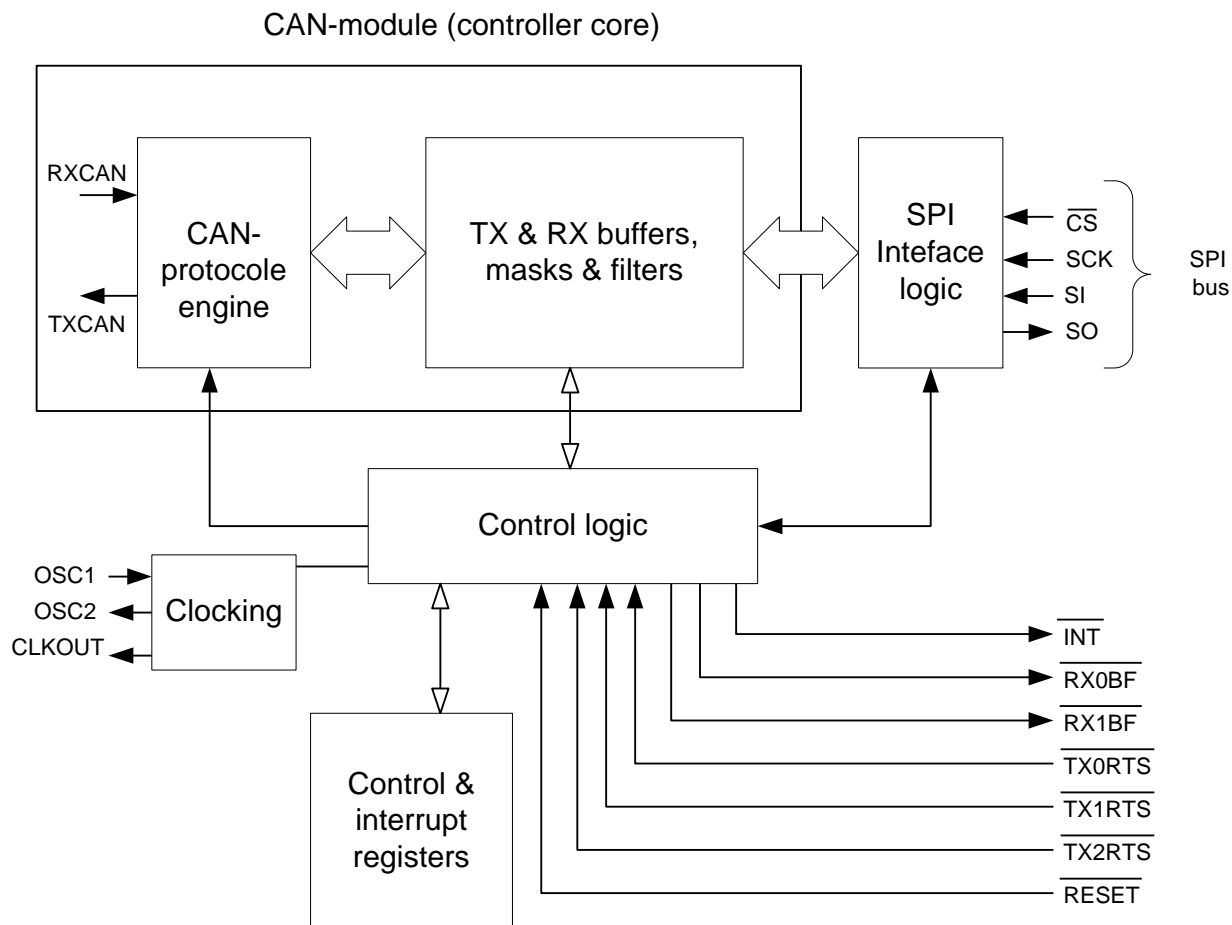


Fig 4 – Block Diagram

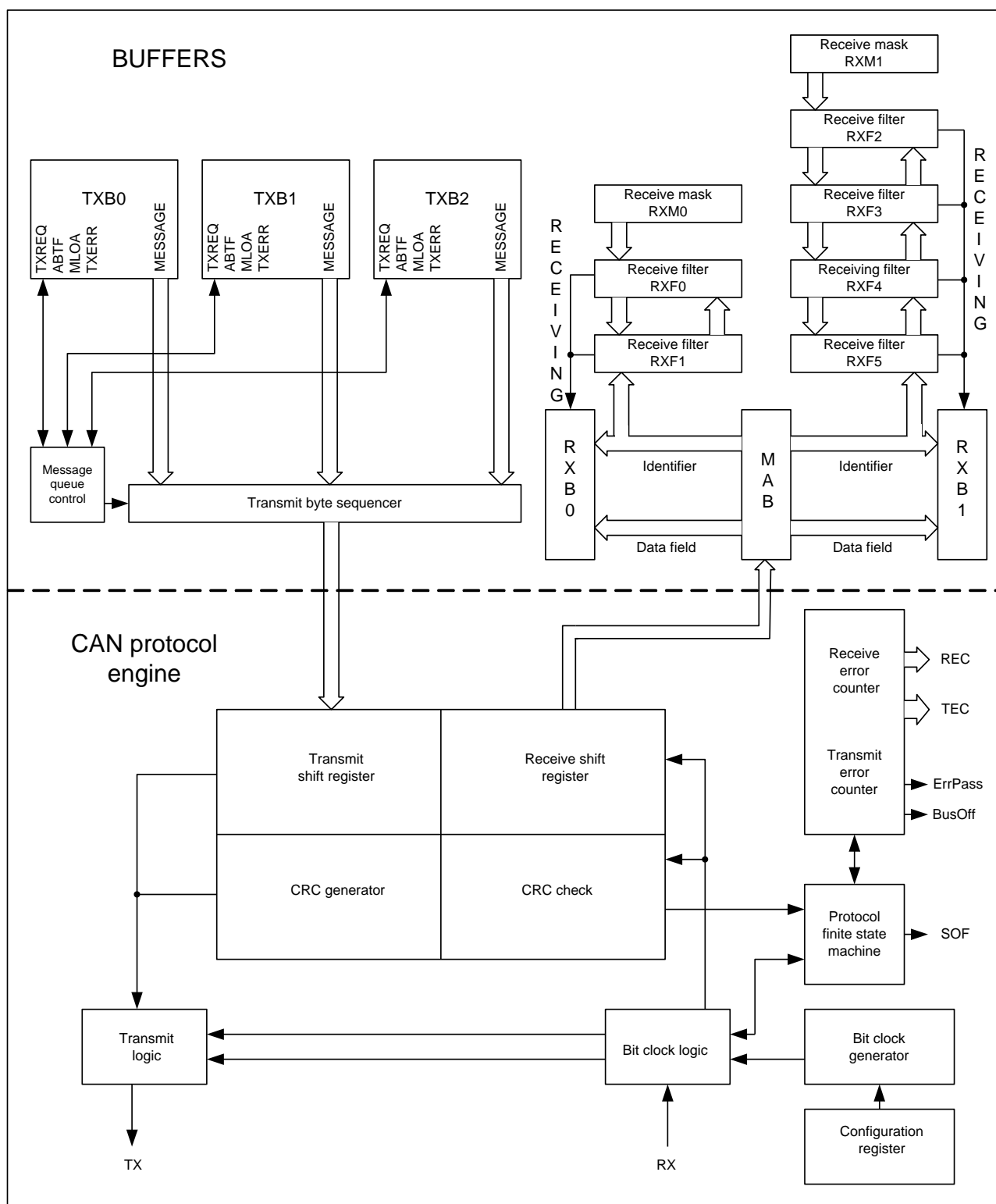


Fig 5 – CAN Module (Controller Core) Block Diagram

ABSOLUTE MAXIMUM RATING

Table 2

Symbol	Parameter	Value		Unit
		Min	Max	
V_{CC}	Supply voltage - for IN2515AN, IN2515ADW - for IN2515BN, IN2515BDW	-	7 7	V
V_I	Input voltage (all pins)	-0.6	$V_{CC}+1.0$	V
V_I	Input voltage for RXCAN, \overline{CS} , \overline{TXnRTS} , SCK, SI pins at functional check mode	-0.6	$V_{CC}+1.0$	V
T_a	Ambient (storage) temperature	-60	125	°C

* Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATION MODE

Table 3

Symbol	Parameter	Value		Unit
		Min	Max	
V_{CC}	Supply voltage - for IN2515AN, IN2515ADW - for IN2515BN, IN2515BDW	2.7 4.5	5.5 5.5	V
V_I	Input voltage (all pins)	0	V_{CC}	V
V_I	Input voltage for RXCAN, \overline{CS} , \overline{TXnRTS} , SCK, SI pins at functional check mode	-0.3	$V_{CC}+1.0$	V
T_a	Ambient (operating) temperature - for IN2515AN, IN2515ADW - for IN2515BN, IN2515BDW	-40 -40	85 125	°C

DC ELECTRICAL CHARACTERISTICS

Table 4.

Parameter	Symbol	Value		Test Conditions	Unit
		Min	Max		
Low level output voltage					
TXCAN pin	V_{OL1}	-	.	$I_{OL} = 0.6 \text{ mA}, V_{CC} = 4.5 \text{ V}$	V
$\overline{\text{RXnBF}}$ pin	V_{OL2}	-	0.6	$I_{OL} = 8.5 \text{ mA}, V_{CC} = 4.5 \text{ V}$	
SO, CLKOUT pins	V_{OL3}	-	0.6	$I_{OL} = 2.1 \text{ mA}, V_{CC} = 4.5 \text{ V}$	
$\overline{\text{INT}}$ pin	V_{OL4}	-	0.6	$I_{OL} = 1.6 \text{ mA}, V_{CC} = 4.5 \text{ V}$	
High level output voltage					
TXCAN pin	V_{OH1}	3,8	-	$I_{OH} = -3.0 \text{ mA}, V_{CC} = 4.5 \text{ V}$	V
$\overline{\text{RXnBF}}$ pin	V_{OH2}	3.8	-	$I_{OH} = -3.0 \text{ mA}, V_{CC} = 4.5 \text{ V}$	
SO, CLKOUT pins	V_{OH3}	4.0	-	$I_{OH} = -400 \mu\text{A}, V_{CC} = 4.5 \text{ V}$	
$\overline{\text{INT}}$ pin	V_{OH4}	3.8	-	$I_{OH} = -1.0 \text{ mA}, V_{CC} = 4.5 \text{ V}$	
Low level input leakage current					
RXCAN, SCK, SI, $\overline{\text{CS}}$, $\overline{\text{RESET}}$, CLKOUT, $\overline{\text{RXnBF}}$, SO pins	I_{ILL1}	-	-1	$V_{IN} = 0 \text{ V}$ $V_{CC} = 5.5 \text{ V}$	μA
OSC1 pin	I_{ILL2}	-	-5		
High level input leakage current					
RXCAN, SCK, SI, $\overline{\text{CS}}$, $\overline{\text{RESET}}$, CLKOUT, $\overline{\text{RXnBF}}$, SO pins	I_{ILH1}	-	1	$V_{CC} = 5.5 \text{ V}$ $V_{IN} = 5.5 \text{ V}$	μA
OSC1 pin	I_{ILH2}	-	5		
Operating consumption current	I_{OCC}	-	10	$V_{CC} = 5.5 \text{ V}$ $F_{OSC} = 25 \text{ MHz}$	mA
Standby consumption current					
IN2515ADW, IN2515AN	I_{CCS}	-	5	$V_{CC} = 5.5 \text{ V}$ $V_{IN} = 5.5 \text{ V}$	μA
IN2515BDW, IN2515BN			8		

Note: - for IN2515ADW, IN2515AN T_a from -40 to $+85$ °C,
- for IN2515BDW, IN2515BN T_a from -40 to $+125$ °C

AC PARAMETERS

Table5.

Parameter	Symbol	Value		Test Conditions	Unit
		Min	Max		
CAN- Interface					
Wake-up noise filter	T_{WF}	100	-	$V_{CC} = 5.5 \text{ V}$	ns
RESET pin low level duration	t_{rl}	2	-	$V_{CC} = 2.7 \text{ V}$	μs
IN2515AN, IN2515ADW				$V_{CC} = 4.5 \text{ V}$	
IN2515BN, IN2515BDW					
SPI-interface					
Clock frequency	F_{CLK}	-	10	-	MHz
\overline{CS} setup time	T_{CSS}	50	-	-	ns
\overline{CS} hold time	T_{CSH}	50	-	-	ns
\overline{CS} disable time	T_{CSD}	50	-	-	ns
Data setup time (SI pin)	T_{SU}	10	-	-	ns
Data hold time (SI pin)	T_{HD}	10	-	-	ns
Clock high time	T_{HI}	45	-	-	ns
Clock low time	T_{LO}	45	-	-	ns
Clock delay time	T_{CLD}	50	-	-	ns
Clock enable time	T_{CLE}	50	-	-	ns
Output valid from clock low	T_V	-	45	-	ns
Output hold time (SO pin)	T_{HO}	0	-	-	ns
Output disable time (SO pin)	T_{DIS}	-	100	-	ns

Note: - for IN2515ADW, IN2515AN T_a from -40 to $+85$ °C,
- for IN2515BDW, IN2515BN T_a from -40 to $+125$ °C

FUNCTIONALITY

IN2515AN, IN2515ADW, IN2515BN, IN2515BDW (further IN2515) are stand-alone Controller Area Network (CAN) controllers that implements the CAN specification, version 2.0B. It is capable of transmitting and receiving both standard and extended data and remote frames. The IN2515 has two acceptance masks and six acceptance filters that are used to filter out unwanted messages, thereby reducing the host MCUs overhead.

The IN2515 is designed to interface directly with the Serial Peripheral Interface (SPI) port available on many microcontrollers and supports Mode 0,0 and Mode 1,1. Commands and data are sent to the device via the SI pin, with data being clocked in on the rising edge of SCK. Data is driven out by the MCP2515 (on the SO line) on the falling edge of SCK. The CS pin must be held low while any operation is performed.

The IN2515 expects the first byte after CS lowered to be the instruction/command byte. This means that CS must be raised and then lowered again to input another command.

Table 6 contains complete list of bytes of SPI instruction set. On detail output and input diagram of both operation modes (Mode 0.0 & Mode 1.1) please refer to Fig 15 & 16.

SPI Instruction Set

Table 6

Instruction Name	Instruction Format	Description
RESET	1100 0000	Resets internal registers to default state, set Configuration mode.
READ	0000 0011	Read data from register beginning at selected address
Read RX Buffer	1001 0nm0	When reading a receive buffer, reduces the overhead of a normal read command by placing the address pointer at one of four locations, as indicated by 'n,m'. Note: The associated RX flag bit (CANINTF.RXnIF) will be cleared after bringing CS high.
WRITE	0000 0010	Write data to register beginning at selected address.
Load TX Buffer	0100 0abc	When loading a transmit buffer, reduces the overhead of a normal Write command by placing the address pointer at one of six locations as indicated by 'a,b,c'.
RTS (Message Request-To-Send)	1000 0nnn	Instructs controller to begin message transmission sequence for any of the transmit buffers.
Read Status	1010 0000	Quick polling command that reads several status bits for transmit and receive functions.
RX Status	1011 0000	Quick polling command that indicates filter match and message type (standard, extended and/or remote) of received message.
Bit Modify	0000 0101	Allows the user to set or clear individual bits in a particular register. Note: Not all registers can be bit-modified with this command. Executing this command on registers that are not bitmodifiable will force the mask to FFh.

RESET

The RESET instruction can be used to re-initialize the internal registers of the IN2515 and set Configuration mode. This command provides the same functionality, via the SPI interface, as the RESET pin. The RESET instruction is a single-byte instruction that requires selecting the device by pulling CS low, sending the instruction byte and then raising CS. It is highly recommended that the reset command be sent (or the RESET pin be lowered) as part of the power-on initialization sequence.

READ

The READ instruction is started by lowering the CS pin. The READ instruction is then sent to the IN2515 followed by the 8-bit address (A7 through A0). Next, the data stored in the register at the selected address will be shifted out on the SO pin. The internal address pointer is automatically incremented to the next address once each byte of data is shifted out. Therefore, it is possible to read the next consecutive register address by continuing to provide clock pulses. Any number of consecutive register locations can be read sequentially using this method.

The read operation is terminated by raising the CS pin (Figure 6).

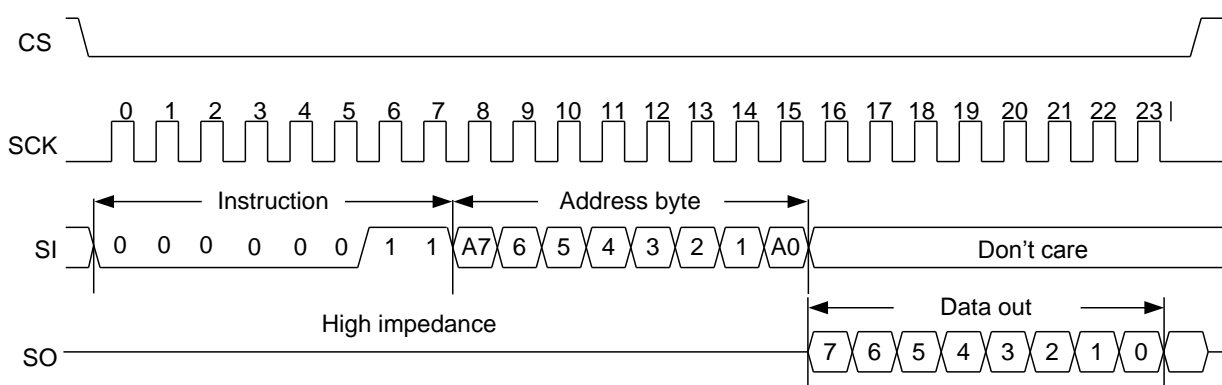


Fig.6 –READ Instruction

Read RX Buffer

The Read RX Buffer instruction (Figure 7) provides a means to quickly address a receive buffer for reading. This instruction reduces the SPI overhead by one byte, the address byte. The command byte actually has four possible values that determine the address pointer location. Once the command byte is sent, the controller clocks out the data at the address location the same as the READ instruction (i.e., sequential reads are possible). This instruction further reduces the SPI overhead by automatically clearing the associated receive flag (CANINTF.RXnIF) when CS is raised at the end of the command.

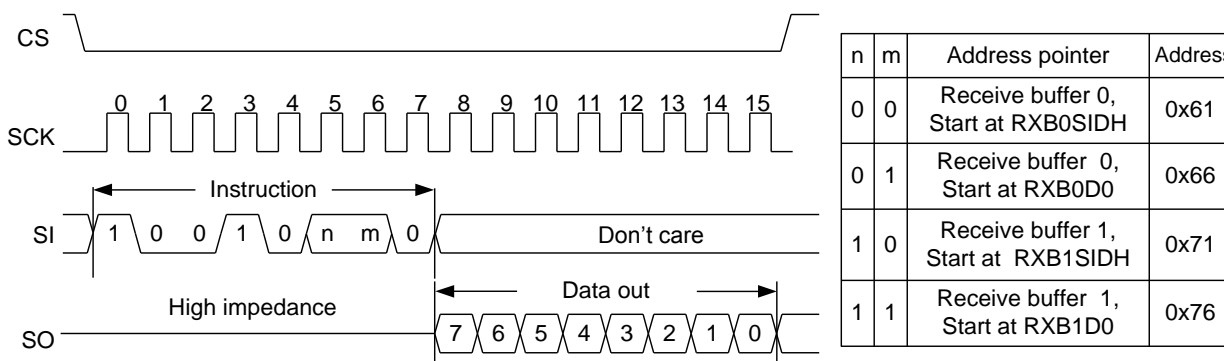


Fig. 7 –READ RX BUFFER instruction

WRITE

The WRITE instruction is started by lowering the CS pin. Then the WRITE instruction is then sent to the IN2515 followed by the address and at least one byte of data. It is possible to write to sequential registers by continuing to clock in data bytes, as long as CS is held low. Data will actually be written to the register on the rising edge of the SCK line for the D0 bit. If the CS line is brought high before eight bits are loaded, the write will be aborted for that data byte and previous bytes in the command will have been written. Refer to the timing diagram in Figure 8 for a more detailed illustration of the byte write sequence.

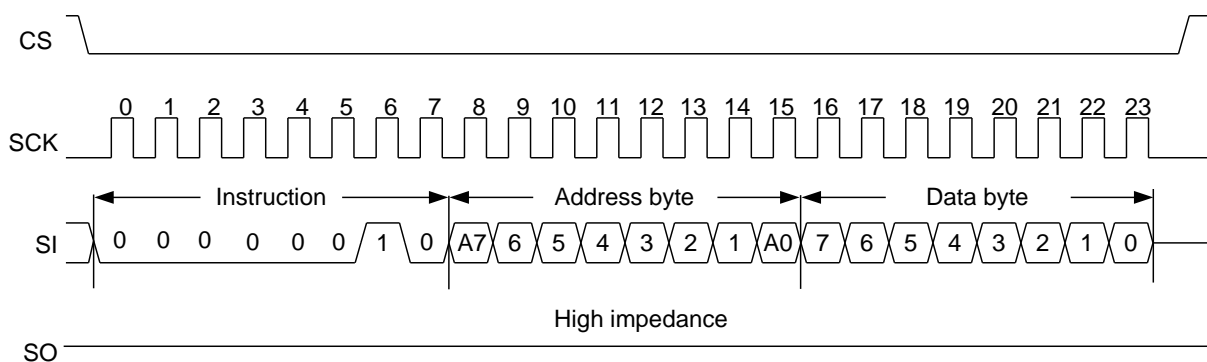


Fig. 8 – BYTE WRITE instruction

Load TX Buffer

The Load TX Buffer instruction (Figure 9) permits to operate without the eight-bit address required by a normal write command. The eight-bit instruction sets the address pointer to one of six addresses to quickly write to a transmit buffer that points to the “ID” or “data” address of any of the three transmit buffers.

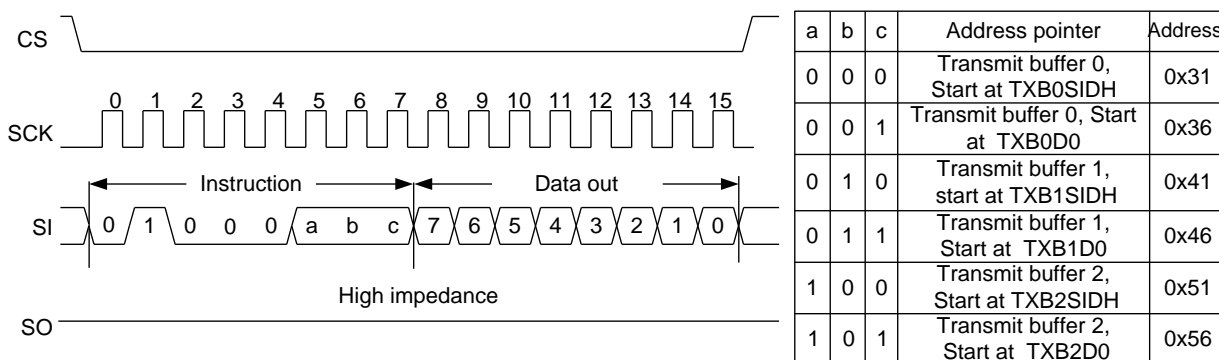


Fig. 9 – LOAD TX BUFFER instruction

Request-To-Send (RTS)

The RTS command can be used to initiate message transmission for one or more of the transmit buffers. The IN2515 is selected by lowering the CS pin. The RTS command byte is then sent. Shown in Figure 10, the last 3 bits of this command indicate which transmit buffer(s) are enabled to send. This command will set the TxBnCTRL.TXREQ bit for the respective buffer(s). Any or all of the last three bits can be set in a single command. If the RTS command is sent with nnn = 000, the command will be ignored.

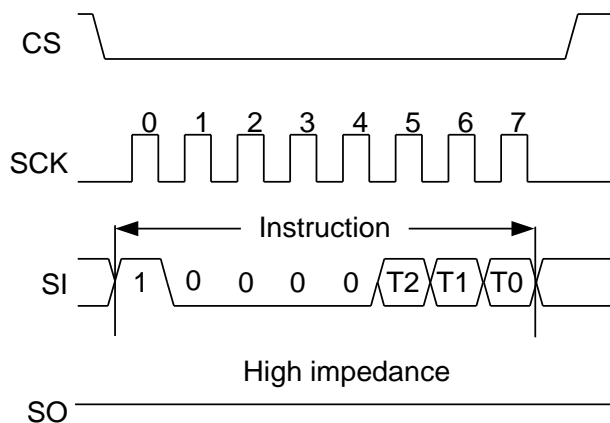


Fig. 10 – REQUEST-TO-SEND instruction (RTS)

Read Status Instruction

The Read Status instruction allows single instruction access to some of the often used status bits for message reception and transmission. The IN2515 is selected by lowering the CS pin and the read status command byte, shown in Figure 11, is sent to the IN2515. Once the command byte is sent, the IN2515 will return eight bits of data that contain the status.

If additional clocks are sent after the first eight bits are transmitted, the IN2515 will continue to output the status bits as long as the CS pin is held low and clocks are provided on SCK.

Each status bit returned in this command may also be read by using the standard read command with the appropriate register address.

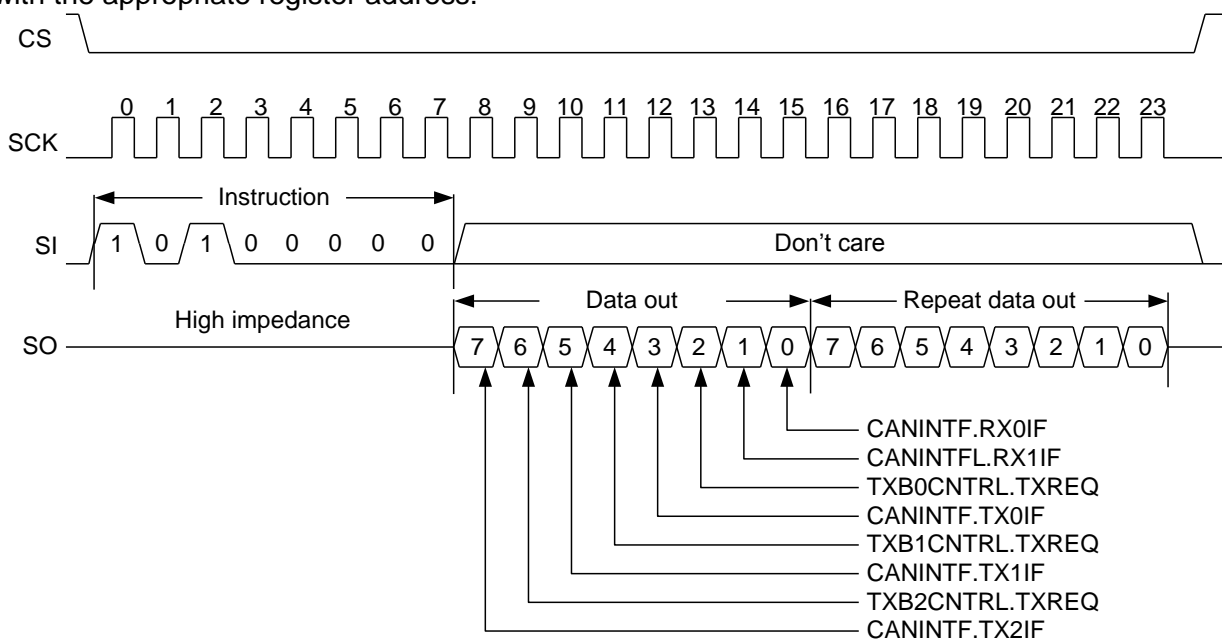


Fig 11 – READ STATUS instruction

RX Status

The RX Status instruction (Figure 12) is used to quickly determine which filter matched the message and message type (standard, extended, remote). After the command byte is sent, the controller will return 8 bits of data that contain the status data. If more clocks are sent after the 8 bits are transmitted, the controller will continue to output the same status bits as long as the CS pin stays low and clocks are provided.

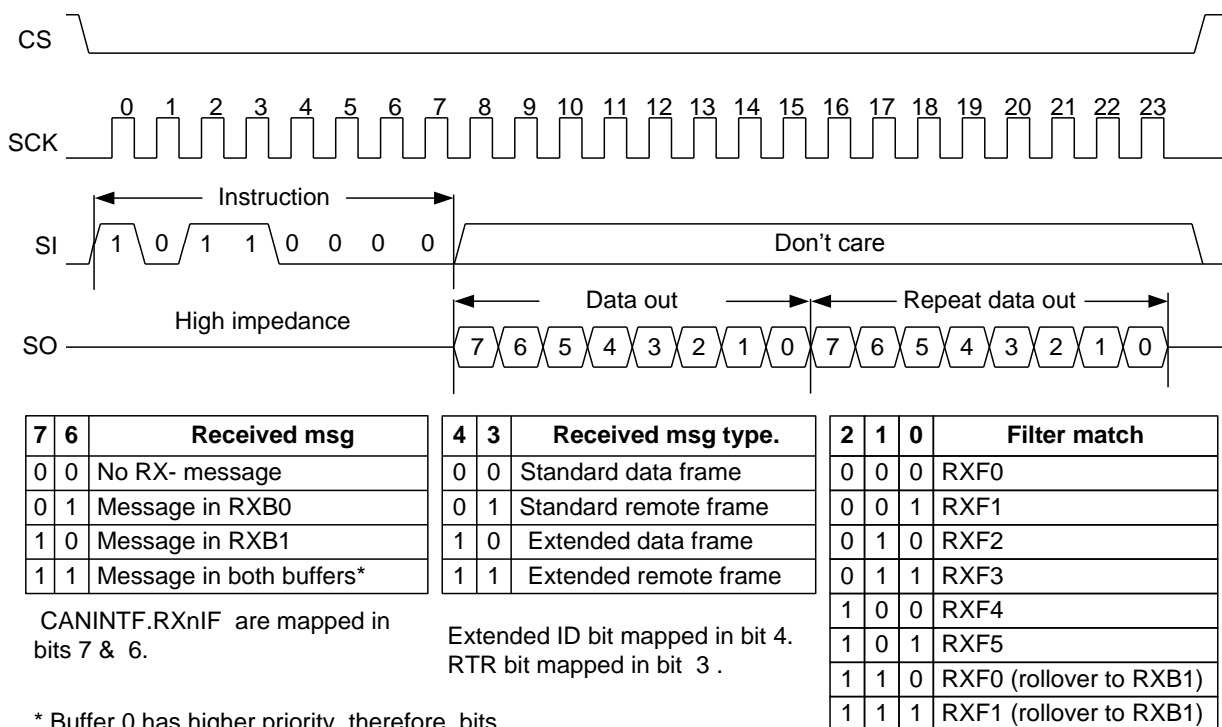


Fig. 12 – RX STATUS instruction

Bit Modify Instruction

The Bit Modify instruction provides a means for setting or clearing individual bits in specific status and control registers. This command is available for registers BFPCTRL, TXRTSCTRL, CANCTRL, CNF3, CNF2, CNF1, CANINTE, CANINTF, EFLG, TXB0CTRL, TXB1CTRL, TXB2CTRL, RXB0CTRL, RXB1CTRL only.

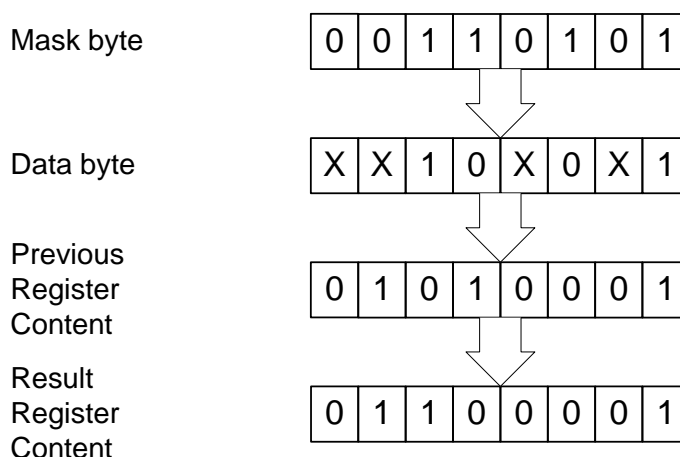


Fig. 13 – Bit Modify instruction

Note: Executing the Bit Modify command on registers that are not bit-modifiable will force the mask to FFh. This will allow bytewrites to the registers, not bit modify.

The chip is selected by lowering the CS pin then the Bit Modify command is applied to the IN2515. The command is followed by the address of the register, the mask byte and finally the data byte. The mask byte determines which bits in the register will be allowed to change. A '1' in the mask byte will allow a bit in the register to change, while a '0' will not.

The data byte determines what value the modified bits in the register will be changed to. A '1' in the data byte will set the bit and a '0' will clear the bit, provided that the mask for that bit is set to a '1' (see Figure 14).

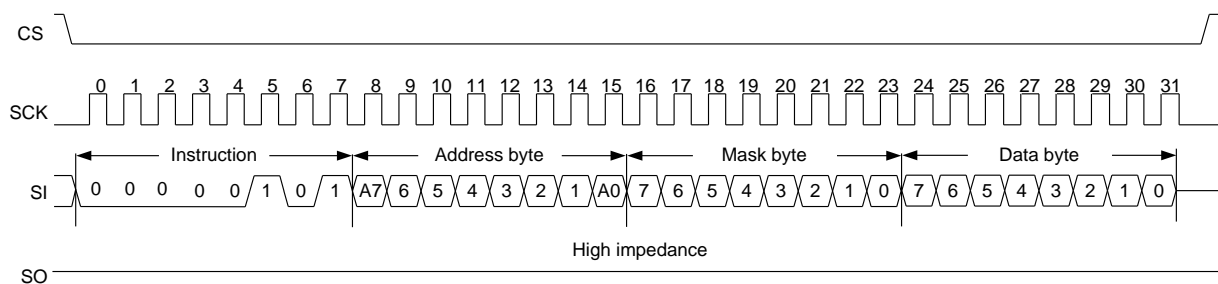


Fig 14 - BIT MODIFY instruction

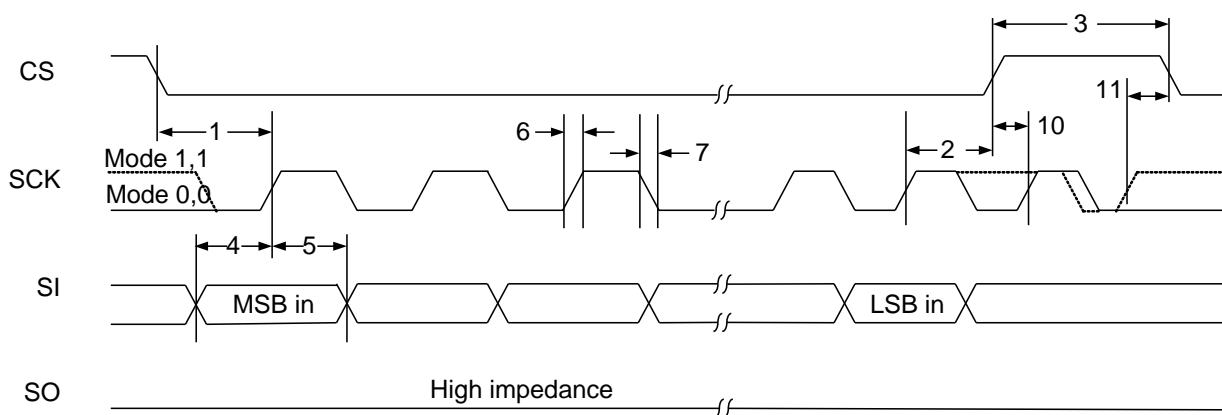


Fig. 15 – SPI- interface input timing

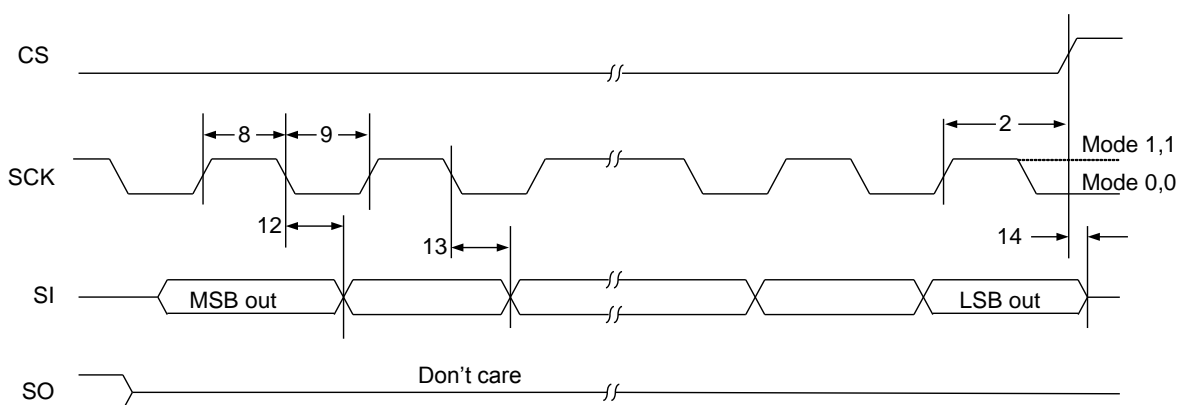


Fig. 16 – SPI- interface output timing

PACKAGE DIMENSIONS

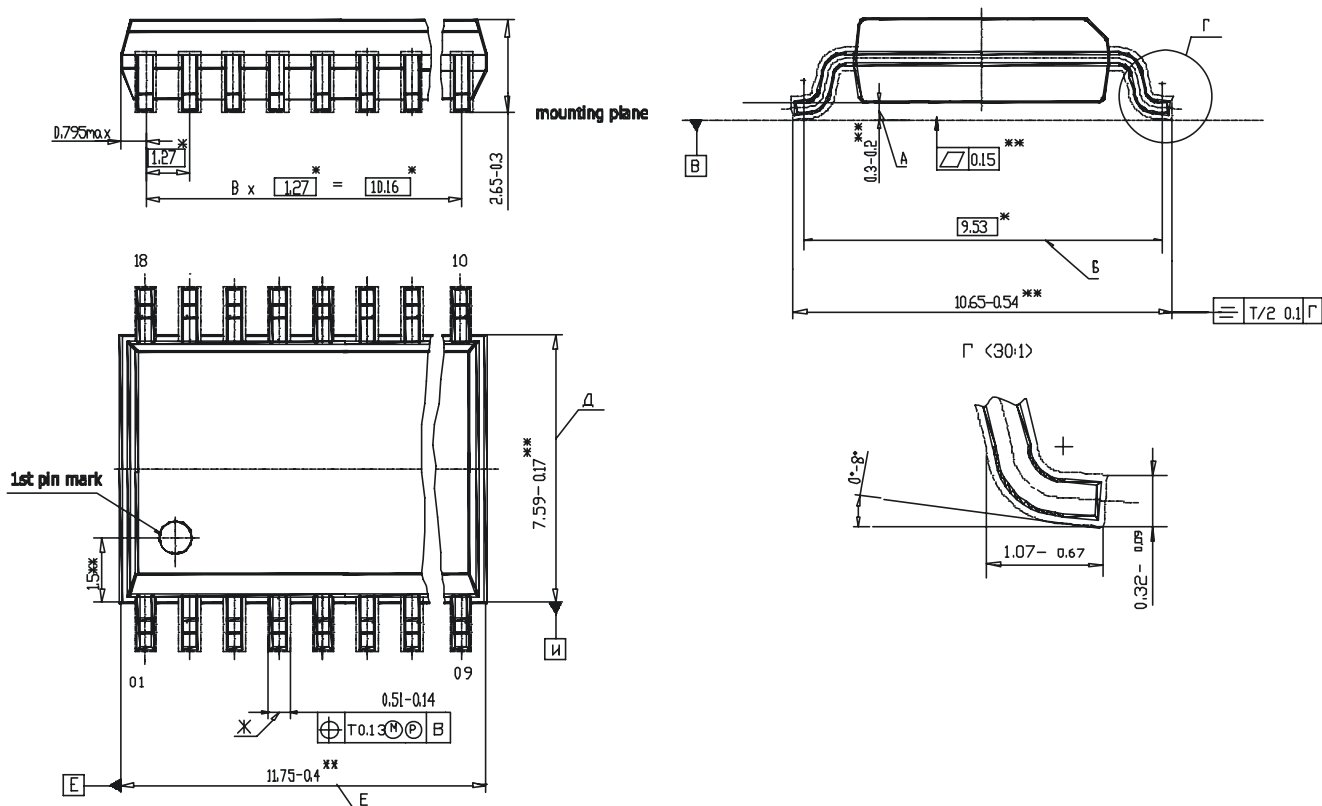


Fig. 17 – 18-Lead Plastic Small Outline (SOIC)

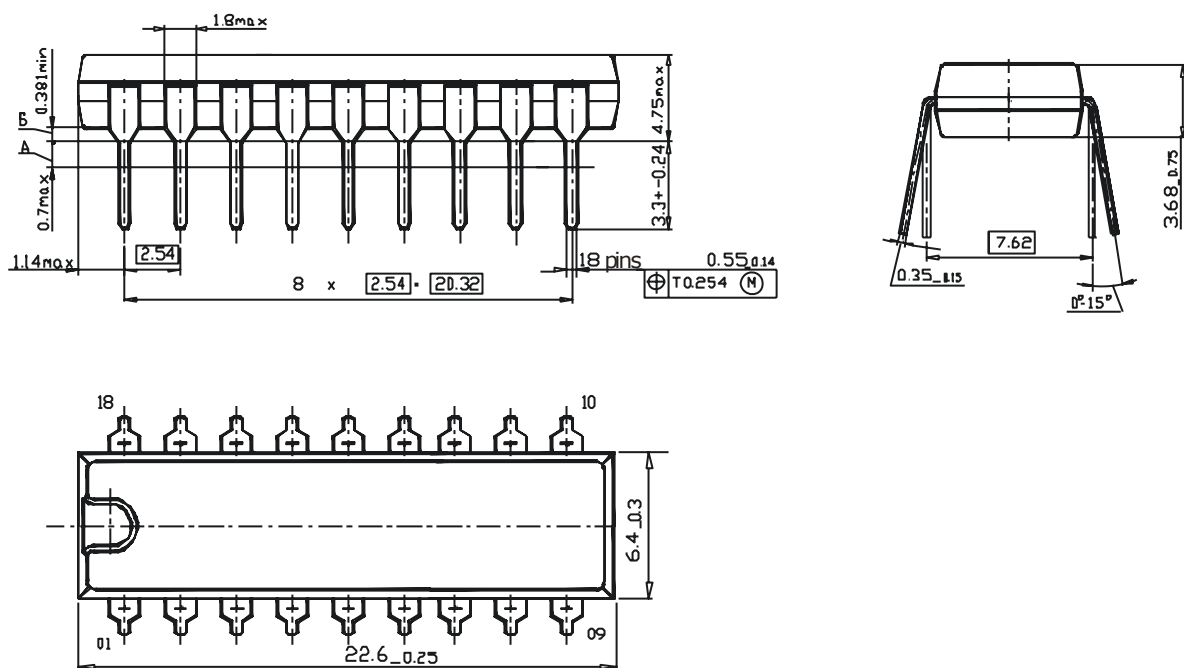
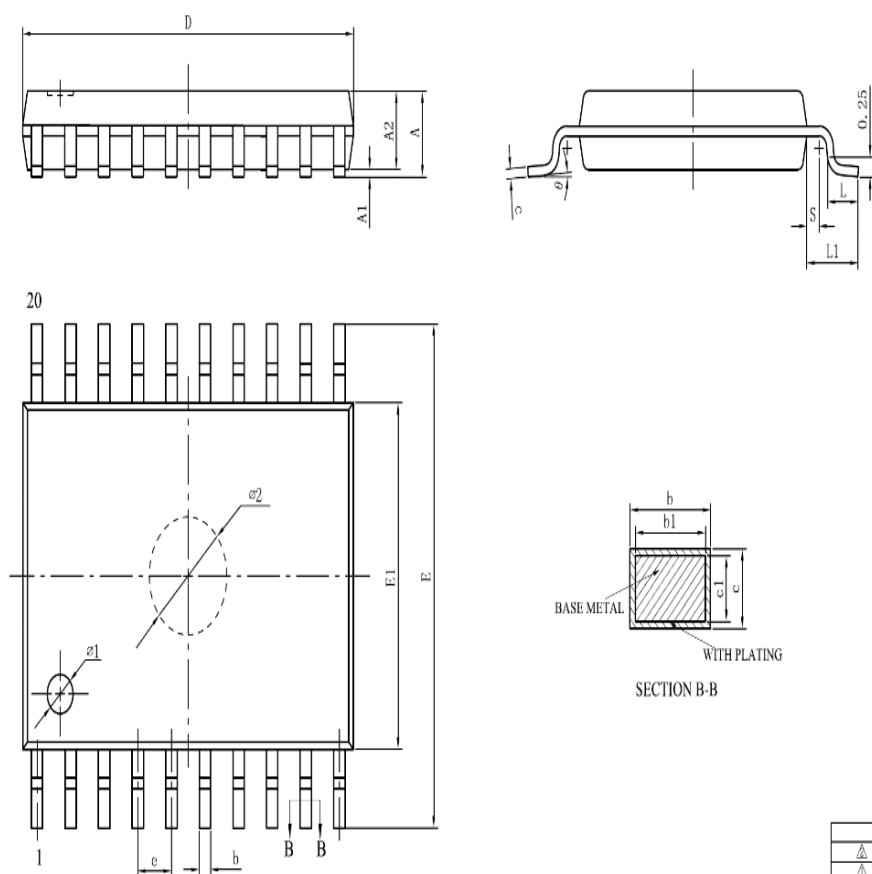


Fig. 18 - 18-Lead Plastic Dual In-line (DIP)



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	—	—	1.20
A1	0.05	—	0.15
A2	0.80	1.00	1.05
b	0.19	—	0.30
b1	0.19	0.22	0.25
c	0.09	—	0.20
c1	0.09	—	0.16
D	6.40	6.50	6.60
E1	4.30	4.40	4.50
E	6.20	6.40	6.60
e	0.65BSC		
L	0.45	0.60	0.75
L1	1.00BSC		
S	0.20	—	—
Ø1	Ø0.8X0.05-0.10DP		
Ø2	Ø1.50X0.05-0.15DP		
θ	0	—	8°
L/载体尺寸 (mil)	118*165 (C)		

△	更改公司名称	李万霞	2011.7.3
△	更改公司名称	李萧锋	2011.3.3
更改标记	更改内容	签名	日期

Fig. 19 - 20-Lead Plastic Thin Shrink Small Outline (TSSOP)